

PNP Silicon General Purpose High Voltage Transistor

MSB92WT1G, MSB92AWT1G

This PNP Silicon Planar Transistor is designed for general purpose amplifier applications. This device is housed in the SC-70/SOT-323 package which is designed for low power surface mount applications.

Features

 These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Symbol	Rating	Value	Unit	
V _{(BR)CBO}	V _{(BR)CBO} Collector-Base Voltage		Vdc	
V _{(BR)CEO}	Collector-Emitter Voltage	-300	Vdc	
V _{(BR)EBO}	V _{(BR)EBO} Emitter-Base Voltage		Vdc	
I _C Collector Current – Continuous		500	mAdc	
ESD	Electrostatic Discharge	MBM > 16,000, MM > 2,000	V	

THERMAL CHARACTERISTICS

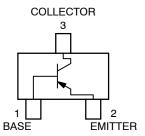
Symbol	Rating	Max	Unit
P _D Power Dissipation (Note 1)		150	mW
T _J Junction Temperature		150	°C
T _{stg}	T _{stg} Storage Temperature Range		°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

 Device mounted on a FR-4 glass epoxy printed circuit board using the minimum recommended footprint.



SC-70 (SOT-323) CASE 419 STYLE 3



MARKING DIAGRAM



xx = Device Code x= 2D or D2 M = Date Code*

= Pb-Free Package

(Note: Microdot may be in either location) *Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†] 3,000/Tape & Reel	
MSB92WT1G	SC-70/ SOT-323 (Pb-Free)	3,000/Tape & Reel	
MSB92AWT1G	SC-70/ SOT-323 (Pb-Free)	3,000/Tape & Reel	

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

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ELECTRICAL CHARACTERISTICS

Symbol	Characteristic	Min	Max	Unit
V _{(BR)CEO}	Collector-Emitter Breakdown Voltage (I _C = -1.0 mAdc, I _B = 0)		-	Vdc
V _{(BR)CBO}	$V_{(BR)CBO}$ Collector-Base Breakdown Voltage (I _C = -100 μAdc, I _E = 0)		-	Vdc
V _{(BR)EBO}	Emitter-Base Breakdown Voltage ($I_E = -100 \mu Adc, I_E = 0$)	-5.0	-	Vdc
Ісво	Collector-Base Cutoff Current (V _{CB} = -200 Vdc, I _E = 0)	-	-0.25	μΑ
I _{EBO}	Emitter-Base Cutoff Current (V _{EB} = -3.0 Vdc, I _B = 0)		-0.1	μΑ
h _{FE1} h _{FE1} h _{FE2} h _{FE3}	DC Current Gain (Note 2) $ \begin{array}{lll} \text{MSB92WT1:} & (\text{V}_{\text{CE}} = -10 \text{ Vdc}, \text{I}_{\text{C}} = -1.0 \text{ mAdc}) \\ \text{MSB92AWT1:} & (\text{V}_{\text{CE}} = -10 \text{ Vdc}, \text{I}_{\text{C}} = -1.0 \text{ mAdc}) \\ & (\text{V}_{\text{CE}} = -10 \text{ Vdc}, \text{I}_{\text{C}} = -10 \text{ mAdc}) \\ & (\text{V}_{\text{CE}} = -10 \text{ Vdc}, \text{I}_{\text{C}} = -30 \text{ mAdc}) \\ \end{array} $	25 120 40 25	_ 200 _ _	1
V _{CE(sat)}	Collector-Emitter Saturation Voltage (Note 2) ($I_C = -20$ mAdc, $I_B = -2.0$ mAdc)	-	-0.5	Vdc
V _{BE(sat)}	V _{BE(sat)} Base–Emitter Saturation Voltage (I _C = -20 mAdc, I _B = -2.0 mAdc)		-0.9	Vdc

SMALL SIGNAL CHARACTERISTICS

f _T	Current – Gain – Bandwidth Product $(I_C = -10 \text{ mAdc}, V_{CE} = -20 \text{ Vdc}, f = 20 \text{ MHz})$	50	-	MHz
C _{cb}	Collector-Base Capacitance (V _{CB} = -20 Vdc, I _E = 0, f = 1.0 MHz)	-	6.0	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 2. Pulse Test: Pulse Width \leq 300 μ s, D.C. \leq 2%.

MSB92WT1G, MSB92AWT1G

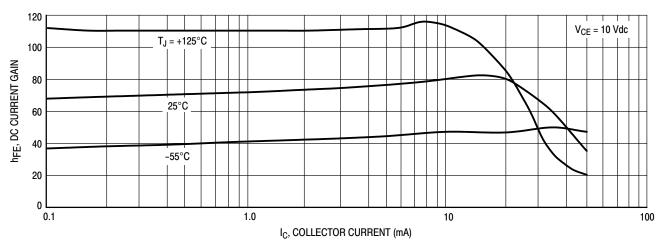


Figure 1. DC Current Gain

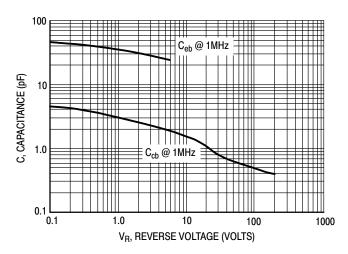
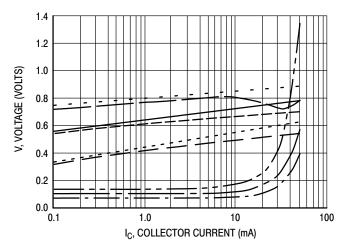


Figure 2. Capacitance



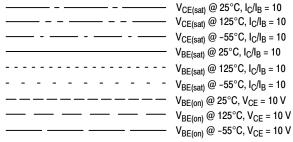


Figure 3. "ON" Voltages







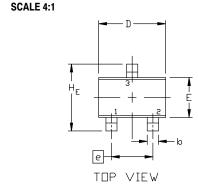
SC-70 (SOT-323) CASE 419 ISSUE R

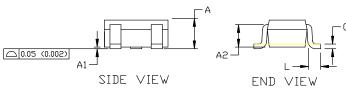
DATE 11 OCT 2022

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH

	MILLIMETERS			INCHES			
DIM	MIN.	N□M.	MAX.	MIN.	N□M.	MAX.	
Α	0.80	0.90	1.00	0.032	0.035	0.040	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
A2		0.70 REF	-	0.028 BSC			
b	0.30	0.35	0.40	0.012	0.014	0.016	
С	0.10	0.18	0.25	0.004	0.007	0.010	
D	1.80	2.00	2.20	0.071	0.080	0.087	
E	1.15	1.24	1.35	0.045	0.049	0.053	
е	1.20	1.30	1.40	0.047	0.051	0.055	
e1	0.65 BSC				0.026 BS	C	
L	0.20	0.38	0.56	0.008	0.015	0.022	
HE	2.00	2.10	2.40	0.079	0.083	0.095	





GENERIC MARKING DIAGRAM

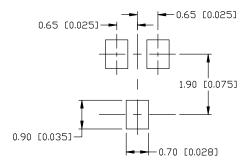


XX = Specific Device Code

M = Date Code

■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



For additional information on our Pb-Free strategy and soldering details, please download the IIN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

SOLDERING FOOTPRINT

STYLE 1: CANCELLED	STYLE 2: PIN 1. ANODE 2. N.C. 3. CATHODE	STYLE 3: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 4: PIN 1. CATHODE 2. CATHODE 3. ANODE	STYLE 5: PIN 1. ANODE 2. ANODE 3. CATHODE	
STYLE 6:	STYLE 7:	STYLE 8:	STYLE 9:	STYLE 10:	STYLE 11:
PIN 1. EMITTER	PIN 1. BASE	PIN 1. GATE	PIN 1. ANODE	PIN 1. CATHODE	PIN 1. CATHODE
2. BASE	2. EMITTER	2. SOURCE	2. CATHODE	2. ANODE	CATHODE
COLLECTOR	COLLECTOR	3. DRAIN	CATHODE-ANODE	3. ANODE-CATHODE	CATHODE

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DESCRIPTION:	SC-70 (SOT-323)		PAGE 1 OF 1	

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